

Description

The CMN3003GF5 is the N-Channel enhancement mode power field effect transistors with high cell density, trench technology. This high density process and design have been optimized switching performance and especially tailored to minimize on-state resistance.

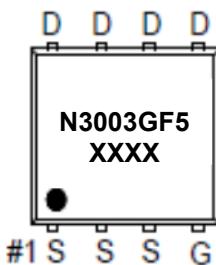
Features

- V_{DS}: 30V
- I_D: 133A
- R_{DS(on)} (@V_{GS}=10V) : < 2.6mΩ
- R_{DS(on)} (@V_{GS}=6V) : < 3.0mΩ
- High density cell design for extremely low R_{DS(on)}
- Excellent on-resistance and DC current capability

Applications

- Battery management
- Power management
- Load switch

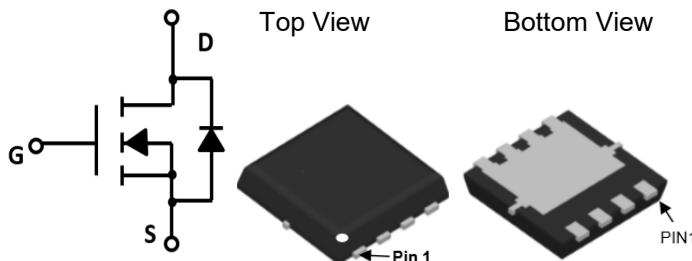
Marking Information



Marking Code =N3003GF5

Date Code = XXXX

Equivalent Circuit and Pin Configuration



Ordering Information

Part Number	Packaging	Reel Size
CMN3003GF5	5000/Tape & Reel	13 inch

Absolute Maximum Ratings (TA=25 °C unless otherwise noted)

Parameter	Symbol	Maximum	Unit
Drain-source Voltage	V _{DS}	30	V
Gate-source Voltage	V _{GS}	±20	V
Drain Current ⁽¹⁾⁽⁶⁾	I _D	133	A
		80	A
	I _D	38	A
		14	A
Pulsed Drain Current ⁽³⁾	I _{DM}	266	A
Total Power Dissipation ⁽⁴⁾	P _D	78	W
		6.3	W
Thermal Resistance Junction-to-Ambient ⁽²⁾⁽⁵⁾	R _{θJA}	20	°C/W
Thermal Resistance Junction-to-Case	R _{θJC}	1.6	°C/W
Junction and Storage Temperature Range	T _{J,TSTG}	-55 to +150	°C

Electrical Characteristics (T_J=25 °C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V, I _D =250μA	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =24V, V _{GS} =0V, T _C =25°C			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1		3	V
Static Drain-Source on-Resistance	R _{D(on)}	V _{GS} =10V, I _D =20A		2.0	2.6	mΩ
		V _{GS} =6V, I _D =20A		2.3	3.0	
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V		0.8	1.2	V
Maximum Body-Diode Continuous Current	I _S				133	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =20V, V _{GS} =0V, f=1MHz		3760		pF
Output Capacitance	C _{oss}			720		
Reverse Transfer Capacitance	C _{rss}			650		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =20V, I _D =20A		78		nC
Gate Source Charge	Q _{gs}			11		
Gate Drain Charge	Q _{gd}			25		
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DD} =20V, I _D =20A, R _{GEN} =3Ω		27		ns
Turn-on Rise Time	t _r			23		
Turn-off Delay Time	t _{D(off)}			96		
Turn-off Fall Time	t _f			49		

Noted: (1) Pulse Test: Pulse Width≤300us,Duty cycle ≤2%.

- (2) The value of R_{θJA} is measured with the device mounted on lin2 FR-4 board with 2oz.Copper,in a still air environment with T_A =25°C.The Power dissipation PDSM is based on R_{θJA} t≤10s and the maximum allowed junction temperature of 150°C.The value in any given application depends on the user's specific board design.
- (3) Single pulse width limited by junction temperature T_{J(MAX)} = 150°C.
- (4) The power dissipation PD is based on T_{J(MAX)} = 150°C,using junction-to-case thermal resistance, and is more useful in setting the upper Dissipation limit for cases where additional heatsinking is used.
- (5) The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJA} and case to ambient.
- (6) Drain current limited by maximum junction temperature.

Typical Performance Characteristics

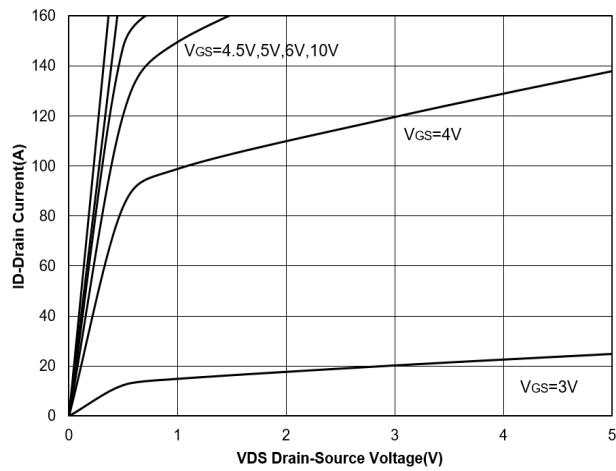


Figure 1. Output Characteristics

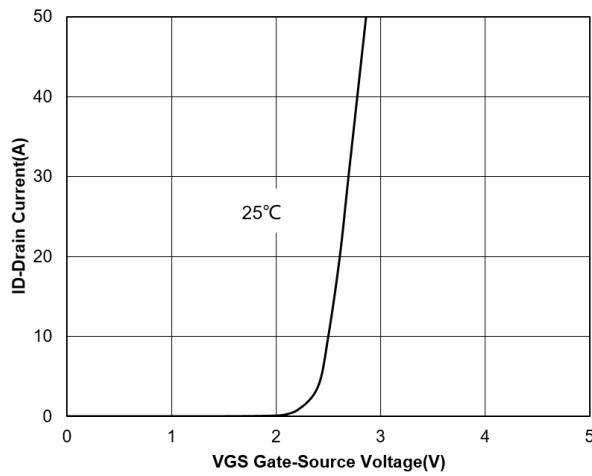


Figure 2. Transfer Characteristics

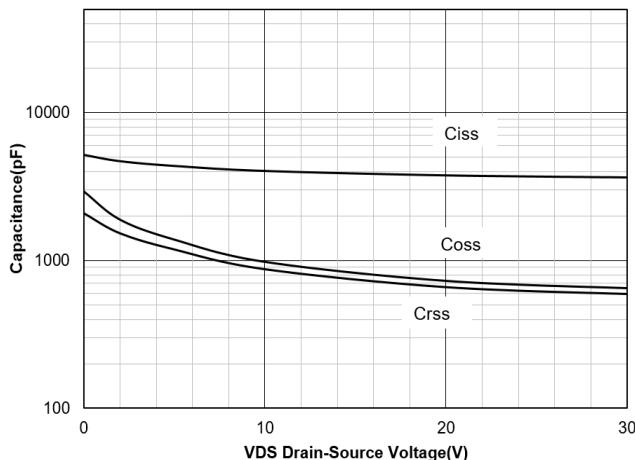


Figure 3. Capacitance Characteristics

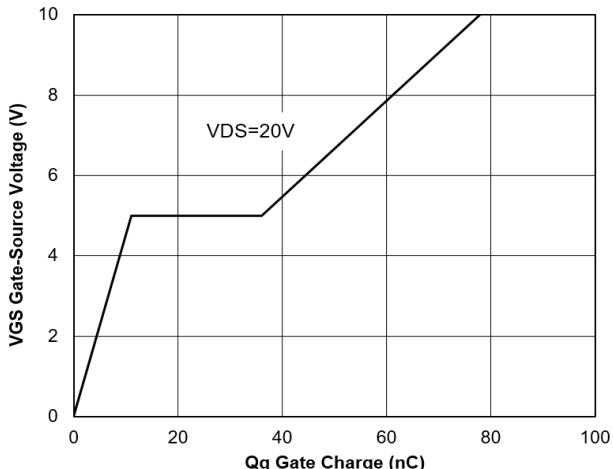


Figure 4. Gate Charge

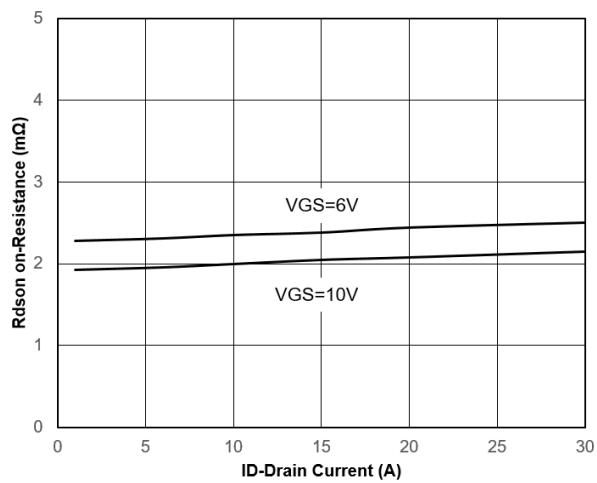


Figure 5. Drain-Source on Resistance

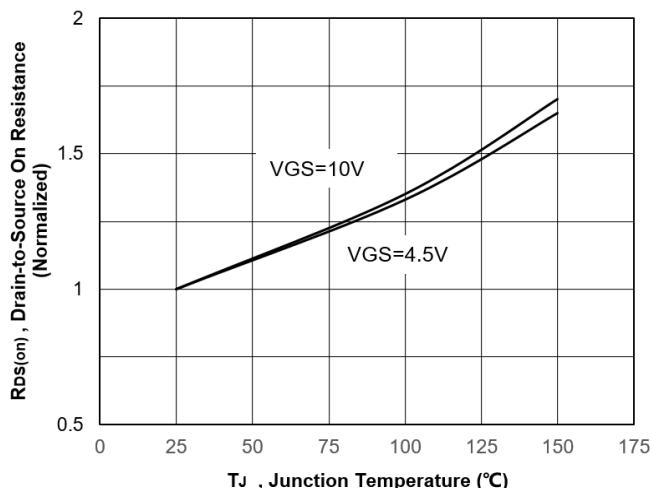


Figure 6. Normalized On-Resistance

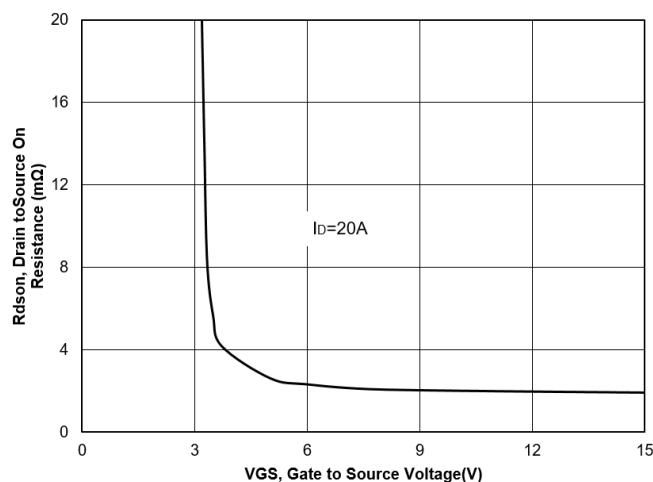


Figure 7. Typical Drain to Source ON Resistance
VS Gate Voltage and Drain Current

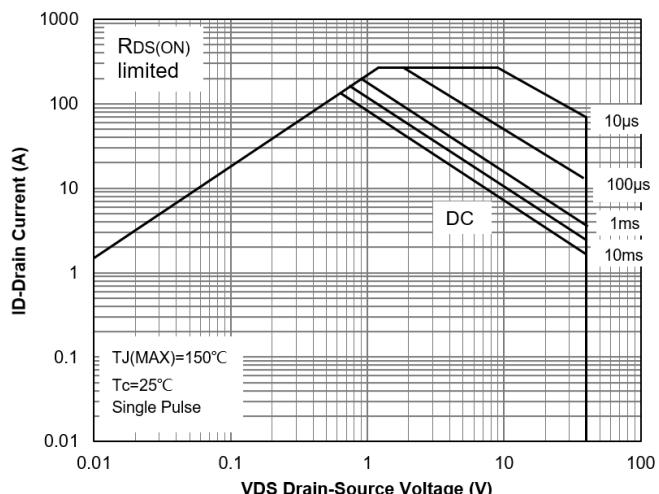


Figure 8. Safe Operation Area

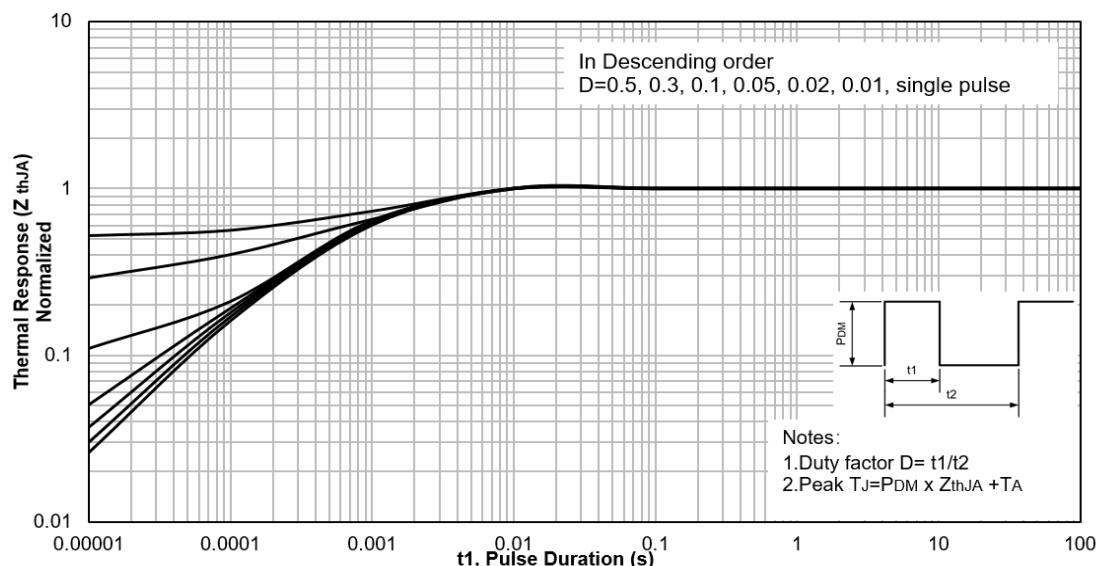


Figure 9. Maximum Effective Transient Thermal Impedance, Junction-to-Case

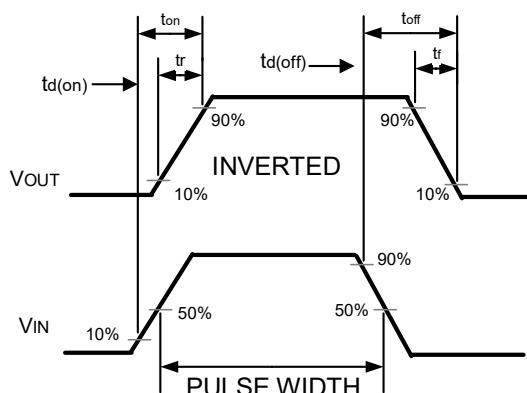
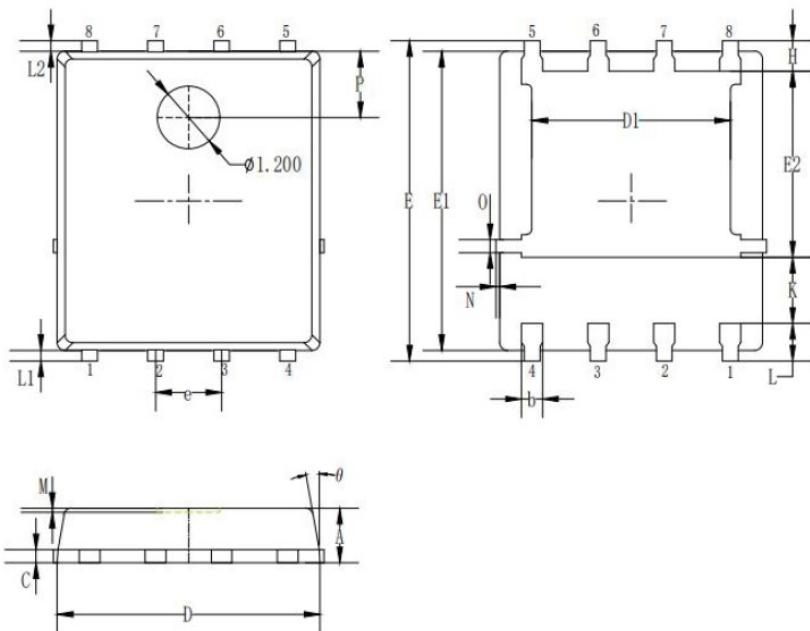


Figure 10. Switching wave

PDFN 5X6 Package Outline Drawing


Symbol	Millimeters		
	Min.	Nom.	Max.
A	0.90	1.05	1.20
b	0.35	0.40	0.50
c	0.20	0.25	0.35
D	4.90	5.05	5.20
D1	3.72	3.82	3.92
E	6.00	6.15	6.30
E1	5.60	5.75	5.90
E2	3.47	3.57	3.67
e	1.27 BSC		
H	0.48	0.58	0.68
K	1.17	1.27	1.37
L	0.64	0.74	0.84
L1/L2	0.20 REF		
θ	8°	10°	12°
M	0.08 REF		
N	0	--	0.15
O	0.25 REF		
P	1.28 REF		

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